

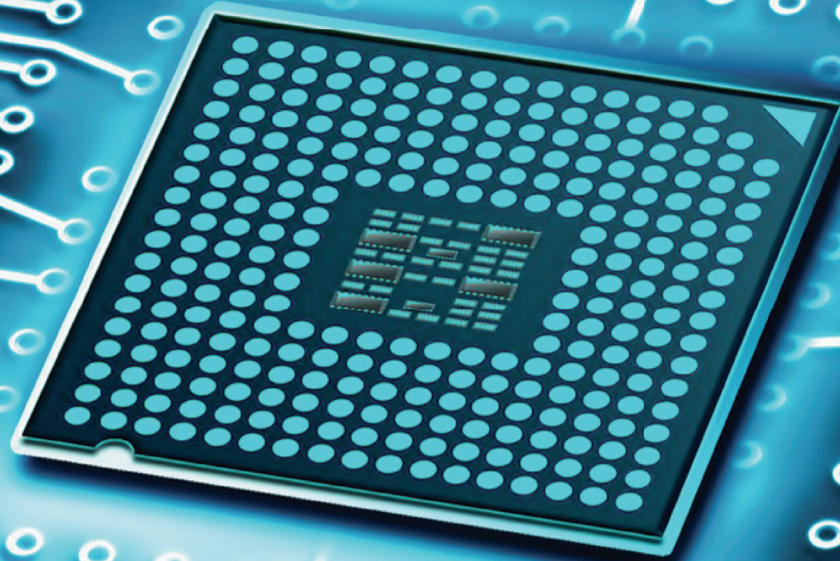
Austrochip 2024

September
25-26

16.06.2024
16.08.2024
25.09.2024
26.09.2024

Paper Submission Deadline
Notification of Acceptance
Tutorials Day
Workshop

CALL FOR PAPERS
TU Wien | Vienna | Austria



Austrochip is an annual **workshop focused on micro- and nano-electronic devices and integrated circuits** in Austria and invites abstracts covering a broad range of topics, including but not limited to:

Micro- and Nanoelectronic Devices

- ▶ Simulation of microelectronic devices and processes (TCAD, DTCO, etc.)
- ▶ Device reliability characterization and analysis (Noise/RTN, BTI, SILC, TDDB, etc.)
- ▶ Radiation hardening
- ▶ Robustness of high-power and wide band gap devices and circuits (SiC, GaN, etc.)
- ▶ Emerging technologies and devices (SiGe, 2D materials, etc.)
- ▶ Reliability tests for monitoring and qualification (at wafer-level, package-level, etc.)
- ▶ Device to circuit degradation

Integrated Circuits

- ▶ Analog, mixed-signal, and RF integrated circuits
- ▶ Digital circuits, filters, DSPs, asynchronous designs
- ▶ FPGA design and reconfigurable hardware
- ▶ Design methodology, system-level design, giga scale circuits, network-on-chip
- ▶ Embedded systems and IoT, energy-efficient machine learning, low-power designs, RF systems, security aspects
- ▶ Verification and testing, signal integrity, compact device modeling, timing analysis, reliability simulation, EMC, ESD, radiation effects
- ▶ Emerging technologies, quantum computing, nano CMOS process, subthreshold circuits, sensors, organic and bio-medical electronics
- ▶ Quantum computing, sub-threshold circuits, sensors, organic and biomedical electronics
- ▶ Case studies and prototyping

Author Information

Authors are encouraged to submit extended abstracts with representative data. Accepted papers will be published in IEEE Explore after the conference.



Journal Special Issue

The best papers will receive an invitation to submit an extended version of their contribution for consideration in a Special Issue to be published in the **Microelectronics Engineering Journal**.



31.01.2025
01.05.2025

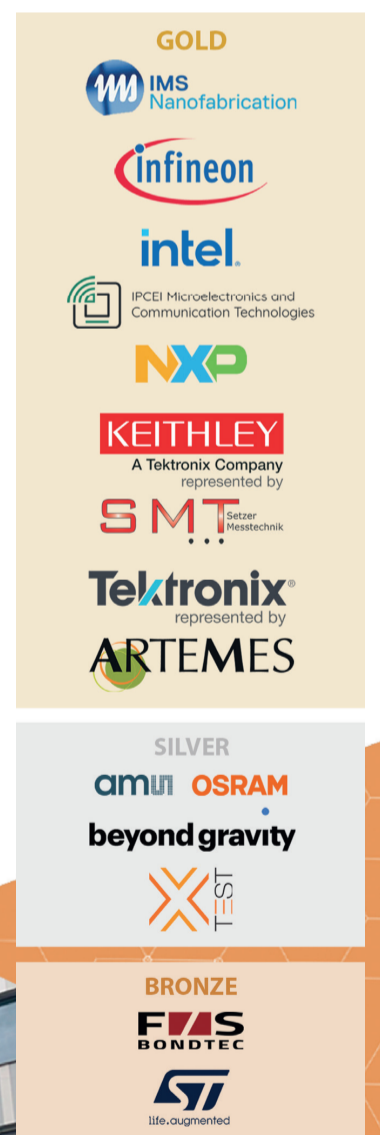
Submission Deadline
Publication of Special Issue

Organizers

Michael Waltl General Chair
Florian Huemer General Chair
Michael Hofbauer Technical Program Chair
Diana Pop Organization and Management

Conference Venue

TU Wien
Faculty of Electrical Engineering and Information Technology
Gußhausstraße 27-29
1040 Vienna
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Austrochip
Workshop on Microelectronics